

Amendments to the Specification:

Please replace paragraph number [0001] with the following:

[0001] This application is a continuation-in-part of copending U.S. Patent Application Serial No. 10/352,699, entitled "Device for Measuring the Profile of a Metal Film Sputter Deposition Target, and System and Method Employing Same," filed January 27, 2003, now U.S. Patent No. 6,811,657 issued on November 2, 2004, the disclosure of which application is incorporated herein by reference.